



General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

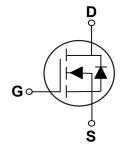
BV _{DSS}	R _{DS(ON)}	Ι _D
40 V	2.5 mΩ	100 A

Features

- $\cdot R_{DS(ON)} \leq 2.5 m\Omega @V_{GS} = 10V$
- Fast Switching
- · Improved dv/dt Capability
- · Green Device Available

PPAK5X6 Pin Configuration





Applications

- · Power Tools
- · Load Switch
- LED Applications
- · LMotor Drive Applications

Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	40	V	
V_{GS}	Gate-Source Voltage	±20	V	
I _D	Drain Current - Continuous (T _C =25°C)	100	Α	
I _{DM}	Drain Current - Pulsed (NOTE 1)	340	Α	
EAS	Single Pulse Avalanche Energy (NOTE 2)	200	mJ	
IAS	Single Pulse Avalanche Current (NOTE 2)	20	Α	
P_{D}	Power Dissipation (T _C =25°C)	73.5	W	
T_J	Operating Junction Temperature Range	-55 to 150	°C	
T _{STG}	Storage Temperature Range	-55 to 150	°C	
//arking Code		ND2P5A		

Thermal Characteristics					
Symbol Parameter		Rating	Unit		
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	62	°C/W		
R _{BJC} Thermal Resistance Junction to Case		1.7	°C/W		





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	40			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} =32V , V_{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =20A			2.5	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	2.0		4.0	V

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			71		
Q_gs	Gate-Source Charge	V_{DS} =20V , V_{GS} =10V , I_{D} =40A		14		nC
Q_{gd}	Gate-Drain Charge			13		
$T_{d(on)}$	Turn-On Delay Time			15		
T _r	Rise Time	V_{DD} =20V , V_{GS} =10V , R_{G} =3 Ω ,		60		nS
$T_{d(off)}$	Turn-Off Delay Time	I _D =40A		97		113
T_f	Fall Time] [35.5		
C_{iss}	Input Capacitance			4150		
C _{oss}	Output Capacitance	V _{DS} =20V , V _{GS} =0V , F=1MHz		400		pF
C_{rss}	Reverse Transfer Capacitance			378		
R_g	Gate resistance	V_{GS} =0V , V_{DS} =0V , f=1MHz		2		Ω

Drain-Source Diode Characteristics and Ratings

9	Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
	Is	Continuous Source Current	V _G =V _D =0V, Force Current			100	Α
	V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A			1	V

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. V_{DD} =25V, V_{GS} =10V, L=1mH, I_{AS} =20A.
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 4. Essentially independent of operating temperature.





Characteristics Curves

FIG. 1-Drain Current

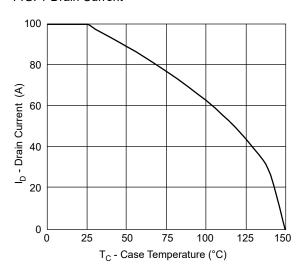


FIG. 2-Normalized $V_{GS(th)}$ vs T_J

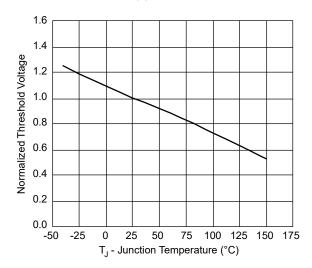


FIG. 3-Normalized $R_{\text{DS}(\text{ON})}\,\text{vs}\;T_{\text{J}}$

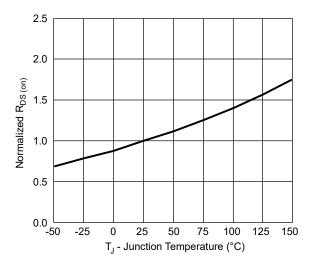


FIG. 4-Gate Charge Characteristics

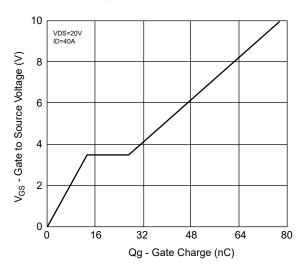


FIG. 5-Safe Operation Area

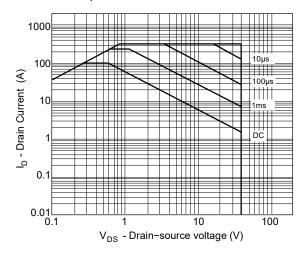
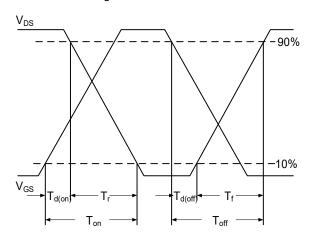


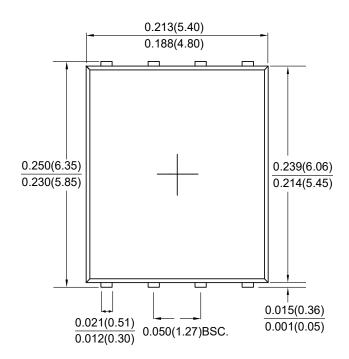
FIG. 6 - Switching Time Waveform

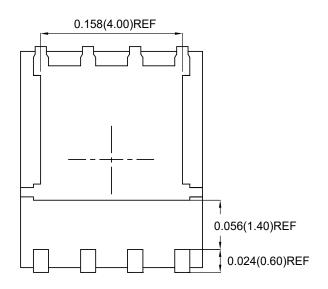




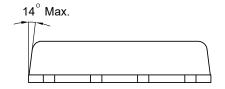


Package Outline Dimensions









PPAK5X6

Dimensions in inches and (millimeters)





LEGAL DISCLAIMER

- The product is provided "AS IS" without any guarantees or warranty. In association with the product, Eris Technology Corporation, its affiliates, and their directors, officers, employees, agents, successors and assigns (collectively, the "Eris") makes no warranties of any kind, either express or implied, including but not limited to warranties of merchantability, fitness for a particular purpose, of title, or of non-infringement of third party rights.
- The information in this document and any product described herein are subject to change without notice and should not be construed as a commitment by Eris. Eris assumes no responsibility for any errors that may appear in this document.
- Eris does not assume any liability arising out of the application or use of this document or any product described herein, any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Eris and all the companies whose products are represented on Eris website, harmless against all damages.
- No license, express or implied, by estoppels or otherwise, to any intellectual property is granted by this document or by any conduct of Eris. Product name and markings notes herein may be trademarks of their respective owners.
- Eris does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.
- Should Customers purchase or use Eris products for any unintended or unauthorized application, Customers shall indemnify and hold Eris and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.
- The official text is written in English and the English version of this document is the only version endorsed by Eris. Any discrepancies or differences created in the translations are not binding and have no legal effect on Eris for compliance or enforcement purposes.